

Title (en)

METHODS OF FABRICATING DEVICES BY LOW PRESSURE COLD WELDING

Title (de)

VERFAHREN ZUM HERSTELLEN VON EINRICHTUNGEN DURCH NIEDERDRUCK-KALTSCHWEISSUNG

Title (fr)

PROCEDES DE FABRICATION DE DISPOSITIFS PAR SOUDAGE A FROID BASSE PRESSION

Publication

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Application

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Abstract (en)

[origin: US2004121568A1] Methods of transferring a metal and/or organic layer from a patterned stamp, preferably a soft, elastomeric stamp, to a substrate are provided. The patterned metal or organic layer may be used for example, in a wide range of electronic devices. The present methods are particularly suitable for nanoscale patterning of organic electronic components.

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H01L 51/40

IPC 8 full level

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Citation (search report)

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